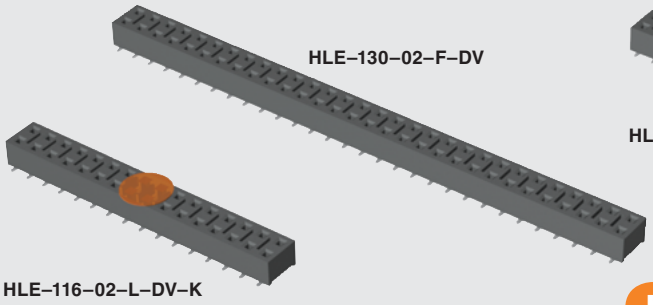
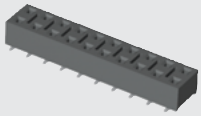
samtec





(2,54 mm) .100"

HLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

Mates With:
TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50µ" (1,27 µm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(1 pin powered per row)
Voltage Rating:
400 VAC
Operating Temp Range:
-55°C to +125°C
Insertion Depth:
(1,78 mm) .070" to
(3,43 mm) .135", pass-through,
or (2,59 mm) .102" min
plus board thickness for
bottom entry
Insertion Force:
(Single contact only)
2 oz (0,56 N) avg.
Withdrawal Force:
(Single contact only)
1.6 oz (0,44 N) avg.
RoHS Compliant:
Yes

TIGER BEAM CONTACT™

Processing:

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0,10 mm) .004" max (02-20)
(0,15 mm) .006" max (21-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594
FILE NO: 090871_0_000

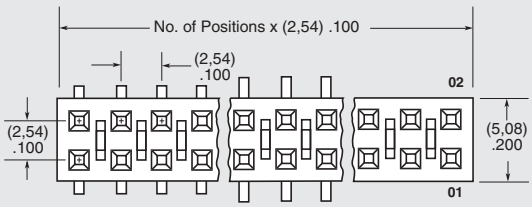
ALSO AVAILABLE
(MOQ Required)

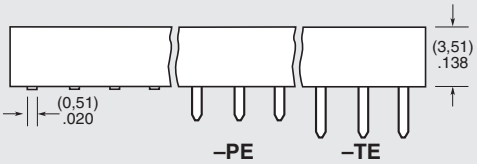
- Other platings
Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

HLE – 1 NO. PINS PER ROW – 02 – PLATING OPTION – DV – TAIL OPTION – OTHER OPTION

02 thru 50

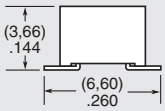




–F
= Gold flash on contact, Matte Tin on tail

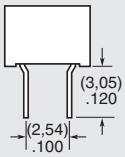
–L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

Leave blank for Surface Mount

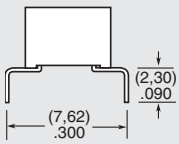


(Requires –BE for Bottom Entry)

–TE
= Through-Hole Top Entry



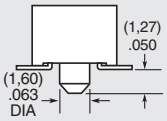
–PE
= Through-hole Pass-Through Entry



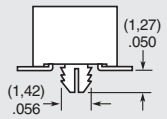
(Requires –BE for Bottom Entry)

–BE
= Bottom Entry (N/A with –TE)

–A
= Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)

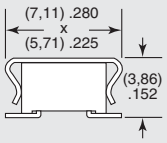


–LC
= Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)



–K
= (6,50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with –TE or –PE tail option

–P
= Metal Pick & Place Pad (3 positions min.)



–TR
= Tape & Reel Packaging (29 positions max.)

Due to technical progress, all designs, specifications and components are subject to change without notice.